
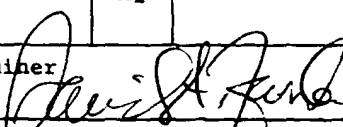
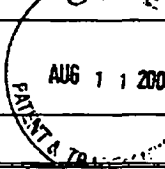
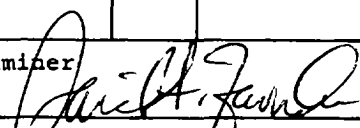


Form PTO-1449				Atty Docket No.		Serial No.		
U.S. Department of Commerce, Patent and Trademark Office				BDG005-1		10/059,686		
INFORMATION DISCLOSURE STATEMENT (Use several sheets if necessary)				Applicant				
				Cheng-Lien Chiang				
				Filing Date		Group Art Unit		
				January 29, 2002		2812		
 U.S. Patent Documents								
*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate	
AT	AA	6,198,171	03/2001	Huang et al.	257	787		
AT	AB	6,218,728	04/2001	Kimura	257	693		
	AC							
	AD							
	AE							
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	AH							
	AI							
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	AK							
	AL							
	AM							
Foreign Patent Documents								
							Translation	
		Document	Date	Country	Class	Subclass	Yes	No
AT	AN	JP-06097352	04/1994	Japan	H01L	23/50	X	
	AO							
Other Art (Including Author, Title, Date, Pertinent Pages, Etc.)								
	AP							
	AQ							
Examiner				Date Considered 12/6/3				
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your next communication to Applicant.								

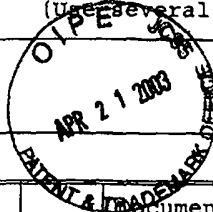
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*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate	
ME	AA	6,001,671	12/1999	Fjelstad	438	112		
ME	AB	6,025,650	02/2000	Tsuji et al.	257	786		
ME	AC	6,281,568	08/2001	Glenn et al.	257	684		
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	AE							
	AF							
	AG							
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Foreign Patent Documents								
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Examiner		Date Considered						
		12/6/13						
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					Filing Date January 29, 2002		Group Art Unit <u>2812 2827</u>	

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*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate	
072	AA	3,627,901	12/1971	Happ	174	52 PE		
	AB	3,678,385	07/1972	Bruner	324	158 F		
	AC	3,930,114	12/1975	Hodge	174	52 FP		
	AD	4,506,238	03/1985	Endoh et al.	333	138		
	AE	5,157,480	10/1992	McShane et al.	357	74		
	AF	5,207,102	05/1993	Takahashi et al.	73	727		
	AG	5,436,500	07/1995	Park et al.	257	696		
	AH	5,677,566	10/1997	King et al.	257	666		
	AI	5,866,939	02/1999	Shin et al.	257	666		
	AJ	5,894,107	04/1999	Lee et al.	174	52.2		
	AK	5,951,804	09/1999	Kweon et al.	156	244.12		
	AL	6,114,770	09/2000	Akram et al.	257	784		
	AM	6,130,116	10/2000	Smith et al.	438	127		
	AN	6,232,152	05/2001	DiStefano et al.	438	124		
	AO	6,297,543	10/2001	Hong et al.	257	666		
	AP	6,303,997	10/2001	Lee	257	778		
	AQ	6,326,700	12/2001	Bai et al.	257	790		
	AR	6,445,077	09/2002	Choi et al.	257	786		
AS	6,455,356	09/2002	Glenn et al.	438	123			
AT	6,468,836	10/2002	DiStefano et al.	438	128			
Foreign Patent Documents								
							Translation	
		Document	Date	Country	Class	Subclass	Yes	No
072	AU	JP-01128897	05/1989	Japan	B42D	15/02		X
	Examiner <i>Janet A. Farache</i>		Date Considered <u>12/6/3</u>					

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				Filing Date January 29, 2002		Group Art Unit 2812 2877		
U.S. Patent Documents								
*Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate		
DH	AA	5,149,958	09/1992	Hallenbeck et al.	250	216		
	AB	5,264,714	11/1993	Nakaya et al.	257	78		
	AC	5,405,809	04/1995	Nakamura et al.	437	209		
	AD	5,834,835	11/1998	Maekawa	257	680		
	AE	5,834,843	11/1998	Mori et al.	257	723		
	AF	5,859,471	01/1999	Kuraishi et al.	257	666		
	AG	5,893,723	04/1999	Yamanaka	438	65		
	AH	6,265,770	07/2001	Uchiyama	257	698		
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	AJ							
AK								
AL								
AM								
Foreign Patent Documents								
							Translation	
	Document	Date	Country	Class	Subclass	Yes	No	
DH	AN	JP-57100761	06/1982	Japan	H01L	27/14		X
	AO							
Other Art (Including Author, Title, Date, Pertinent Pages, Etc.)								
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	AQ							
Examiner D. H. Farnh		Date Considered 12/6/3						
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U.S. Department of Commerce, Patent and Trademark Office	BDG005-1	10/059686
INFORMATION DISCLOSURE STATEMENT (Use several sheets if necessary)	Applicant Cheng-Lien Chiang	
	Filing Date	Group Art Unit 2827

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*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
022	AA	5,081,520	01/1992	Yoshii et al.	357	80	
	AB	5,241,133	08/1993	Mullen, III et al.	174	52.4	
	AC	5,394,303	02/28/95	Yamaji	361	749	
	AD	5,665,652	09/1997	Shimizu	438	127	
	AE	5,674,785	10/1997	Akram et al.	437	217	
	AF	5,744,827	04/28/98	Jeong et al.	257	686	
	AG	5,744,859	04/1998	Ouchida	257	668	
	AH	5,804,771	09/1998	McMahon et al.	174	255	
	AI	5,811,879	09/1998	Akram	257	723	
	AJ	5,949,655	09/1999	Glenn	361	783	
	AK	6,013,877	01/2000	Degani et al.	174	264	
	AL	6,143,588	11/2000	Glenn	438	116	
	AM	6,159,770	12/2000	Tetaka et al.	438	112	
022	AN	6,274,927	08/2001	Glenn	257	680	

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022	AO	Crowley, "Socket Developments for CSP and FBGA Packages," Chip Scale Review, May 1998, pp. 37-40.
	AP	Forster, "Socket Challenges for Chip-Scale Packages," Chip Scale Review, May 1998, pp. 43-47.
	AQ	Amagai, "Chip-Scale Packages for Center-Pad Memory Devices," Chip Scale Review, May 1998, pp. 68-77.
022	AR	Vandeveld et al., "The PSGA, a Lead-Free CSP for High Performance & High Reliable Packaging," Proceedings of the 2001 International Symposium on Microelectronics, October 9, 2001, pp. 260-265.

Examiner <i>David H. Fain</i>	Date Considered 12/6/03
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U.S. Department of Commerce, Patent and Trademark Office		BDG005-1	101059686
INFORMATION DISCLOSURE STATEMENT (Use several sheets if necessary)		Applicant Cheng-Lien Chiang	
		Filing Date 1/29/02	Group Art Unit 2827
*Examiner Initial	Other Art (Including Author, Title, Date, Pertinent Pages, Etc.)		
PA	AA	U.S. Application Serial No. 09/865,367, filed May 24, 2001, entitled "Semiconductor Chip Assembly With Simultaneously Electroplated Contact Terminal and Connection Joint"	
PA	AB	U.S. Application Serial No. 09/864,555, filed May 24, 2001, entitled "Semiconductor Chip Assembly with Simultaneously Electrolessly Plated Contact Terminal and Connection Joint"	
PA	AC	U.S. Application Serial No. 09/864,773, filed May 24, 2001, entitled "Semiconductor Chip Assembly With Ball Bond Connection Joint"	
PA	AD	U.S. Application Serial No. 09/878,649 filed June 11, 2001, entitled "Method of Making a Semiconductor Chip Assembly with a Conductive Trace Subtractively Formed Before and After Chip Attachment"	
PA	AE	U.S. Application Serial No. 09/878,626 filed June 11, 2001, entitled "Method of Connecting a Conductive Trace to a Semiconductor Chip"	
PA	AF	U.S. Application Serial No. 09/917,339 filed July 27, 2001, entitled "Method of Connecting a Bumped Compliant Conductive Trace to a Semiconductor Chip"	
PA	AG	U.S. Application Serial No. 09/927,216 filed August 10, 2001, entitled "Semiconductor Chip Assembly with Hardened Connection Joint"	
PA	AH	U.S. Application Serial No. 09/939,140 filed August 24, 2001, entitled "Semiconductor Chip Assembly with Interlocked Conductive Trace"	
PA	AI	U.S. Application Serial No. 09/962,754 filed September 24, 2001, entitled "Method of Connecting a Conductive Trace and an Insulative Base to a Semiconductor Chip"	
PA	AJ	U.S. Application Serial No. 09/972,796 filed October 6, 2001, entitled "Method of Connecting a Bumped Compliant Conductive Trace and an Insulative Base to a Semiconductor Chip"	
PA	AK	U.S. Application Serial No. 09/997,973 filed November 29, 2001, entitled "Method of Connecting a Bumped Conductive Trace to a Semiconductor Chip"	
Examiner	Date Considered		
David H. Fung	12/6/03		
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